

PUBLICATION NUMBER : 11342483  
PUBLICATION DATE : 14-12-99

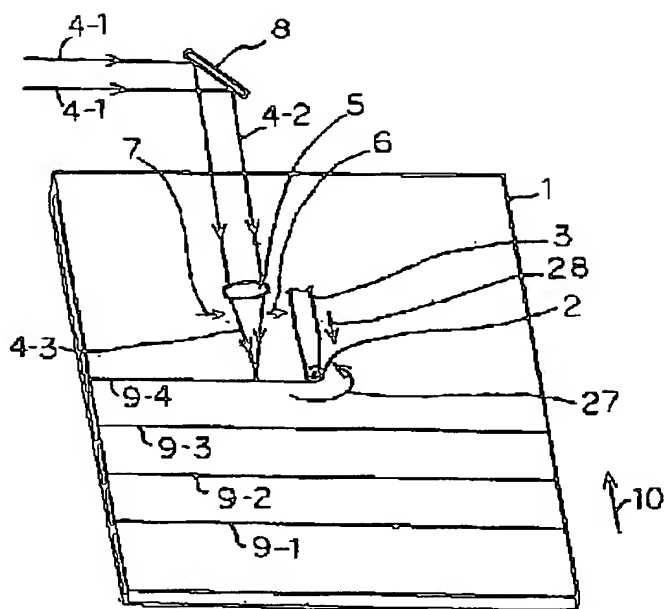
APPLICATION DATE : 22-04-98  
APPLICATION NUMBER : 10112050

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INT.CL. : B23K 26/00 B23K 26/00 B23K 26/08  
B23K 26/14 B28D 5/00 C03B 33/02  
C03B 33/09

TITLE : METHOD AND DEVICE FOR  
PROCESSING SUBSTRATE



ABSTRACT : PROBLEM TO BE SOLVED: To provide a substrate processing method and its processing device for realizing miniaturization and lightening, and obtaining a substrate with high dimensional accuracy.

SOLUTION: Marking-off lines on a non-metallic material substrate 1 by a cutter 2 are formed to be narrow in width, and shallow. Since cracks 9-1-9-4 occur by irradiating the marking-off lines with a CO<sub>2</sub> laser beam and make the substrate 1 easily dividable, not only the substrate 1 can be processed at high dimensional accuracy, but also the occurrence of chipping at the time of forming the marking-off lines can be restrained at a minimum level. Further, since a CO<sub>2</sub> laser device is fixed, it does not require to move the laser device by putting on a mobile stage for moving the laser device in a X direction. The processing device can thus be miniaturized and lightened.

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